6-104068-0 - ACTIVE

AMPMODU | AMPMODU System 50

TE Internal #: 6-104068-0 PCB Mount Header, Vertical, Board-to-Board, 16 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 16

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded

Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	16
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Dielectric Withstanding Voltage (Max)	500 VAC
Insulation Resistance	5000 ΜΩ
Operating Voltage	30 VAC
Body Features	
Connector Profile	Standard
Primary Product Color	Black

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Contact Features

Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Rectangular
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3.6 A
Termination Features	
Round Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	

Mating Retention	With
Mating Retention Type	Latching
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High

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Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
UL Rating	Recognized
Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	31
Packaging Type	Box, Tube
Other	
Position Locations Omitted	0

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Solder Process Capability

vvave solder capable to 260°C

Product Compliance Disclaimer

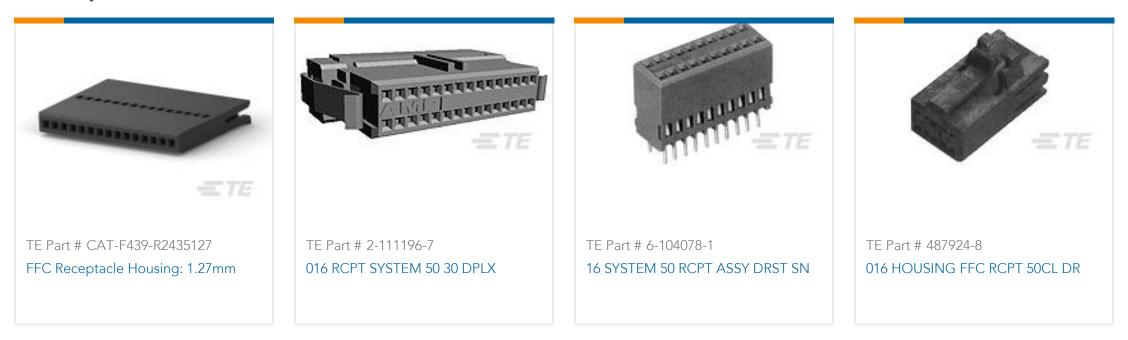
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits

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as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



Also in the Series | AMPMODU System 50



PCB Headers & Receptacles(1012)

Customers Also Bought





Documents

PCB Mount Header, Vertical, Board-to-Board, 16 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50



Product Drawings 16 SYSTEM 50 HDR DRST SHRD

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_6-104068-0_S.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_6-104068-0_S.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_6-104068-0_S.3d_stp.zip

English

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Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Ribbon Cable Interconnect Solutions

English

Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

English